## SUBMINIATURE SOLID STATE LAMP

Part Number: KM2520CGCK08 Green

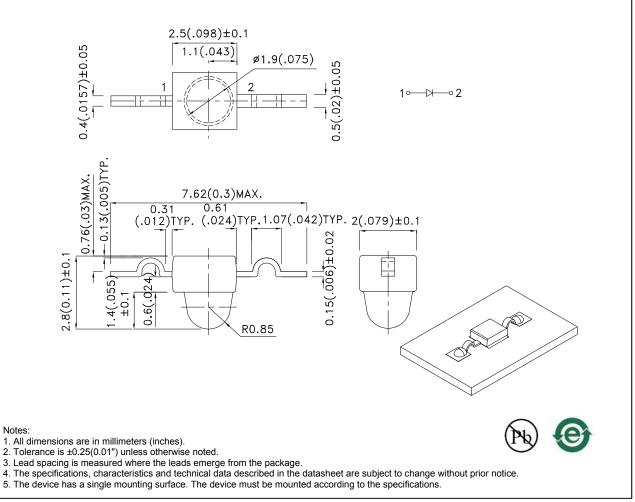
#### **Features**

- Subminiature package.
- Yoke lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

#### Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

#### Package Dimensions



SPEC NO: DSAC3449 APPROVED: WYNEC REV NO: V.8 CHECKED: Allen Liu DATE: DEC/21/2010 DRAWN: Y.H.Wu PAGE: 1 OF 5 ERP: 1202001286

### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KM2520CGCK08	Green (AlGaInP)	Water Clear	400	700	20°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	570		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	IF=20mA
IR	Reverse Current	Green		10	uA	VR=5V

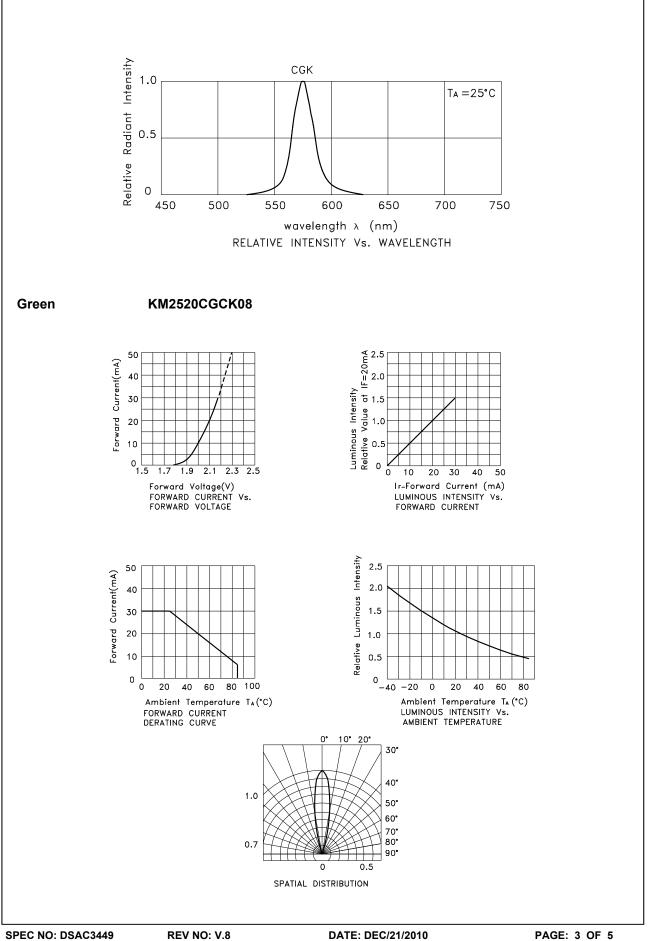
Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

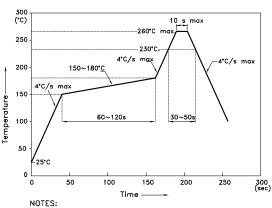
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## **KM2520CGCK08**

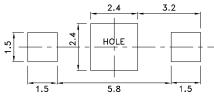
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

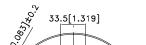
Reflow Soldering Profile For Lead-free SMT Process.



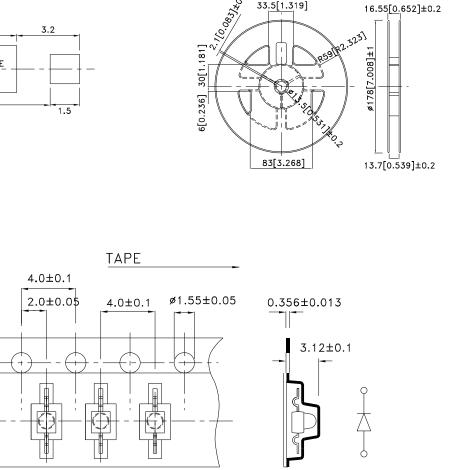
Time — -NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to be temperature. to high temperature. 3.Number of reflow process shall be 2 times or less.







**Reel Dimension** 



**Tape Dimensions** 

1.75±0.1

5±0.05

ц.

 $^{12+0.3}_{-0.1}$ 

(Units : mm)

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